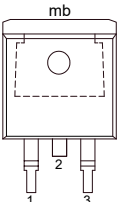


5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	n.c.	no connection	 D2PAK (SOT404)	
2	K	cathode[1]		
3	A	anode		
mb	K	mounting base; cathode		

[1] it is not possible to make a connection to Pin 2 of the SOT404 package

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV29B-500	D2PAK	plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped)	SOT404

7. Limiting values

Table 4. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{RRM}	repetitive peak reverse voltage		-	500	V
V _{RWM}	crest working reverse voltage		-	500	V
V _R	reverse voltage	DC	-	500	V
I _{F(AV)}	average forward current	δ = 0.5 ; T _{mb} ≤ 123 °C; SQW; Fig. 1; Fig. 2	-	9	A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 123 °C; SQW	-	18	A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; SIN t _p = 8.3 ms; T _{j(init)} = 25 °C; SIN	-	100 110	A
T _{stg}	storage temperature		-40	150	°C
T _j	junction temperature		-	150	°C

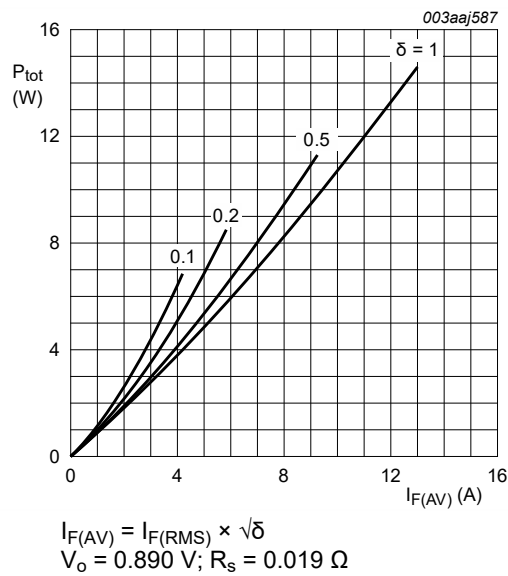


Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values

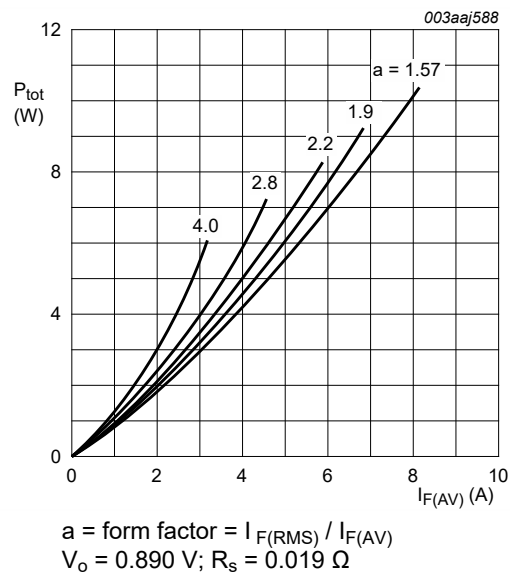


Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 3		-	-	2.5	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	[1]	-	50	-	K/W

[1] Device mounted on a FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

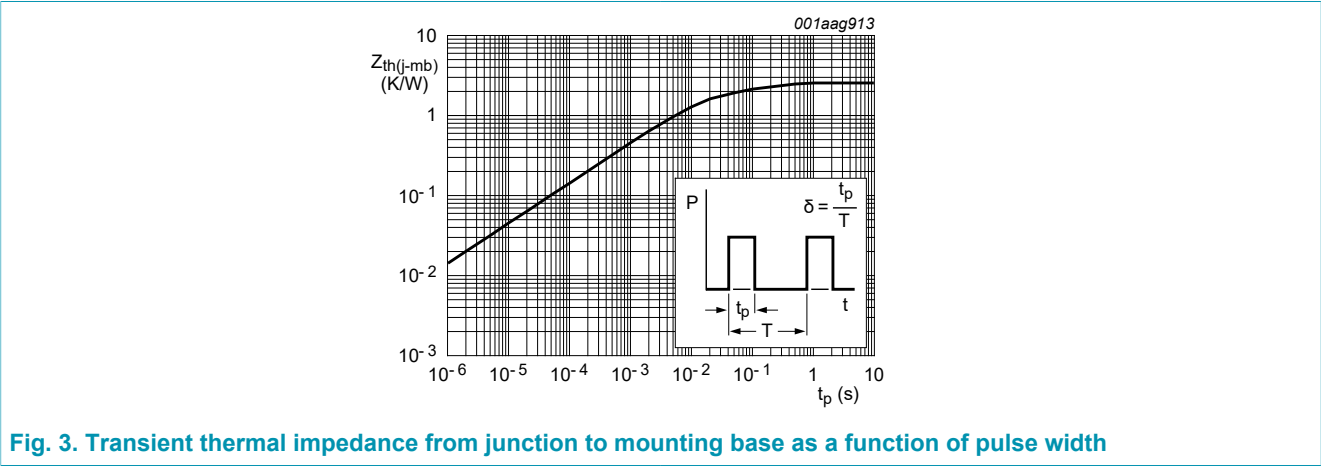
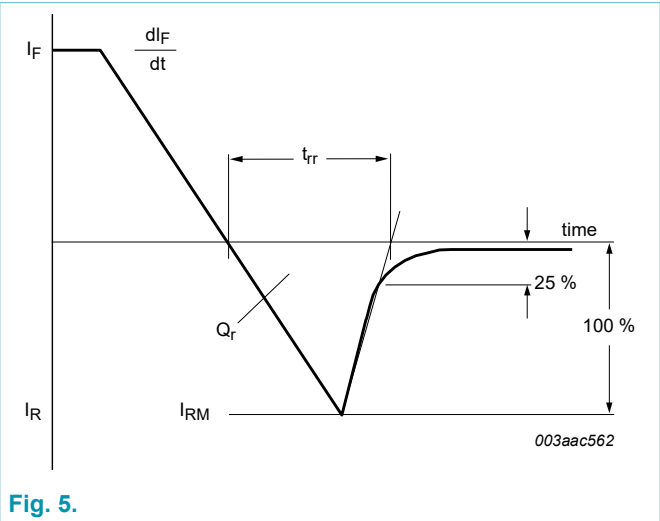
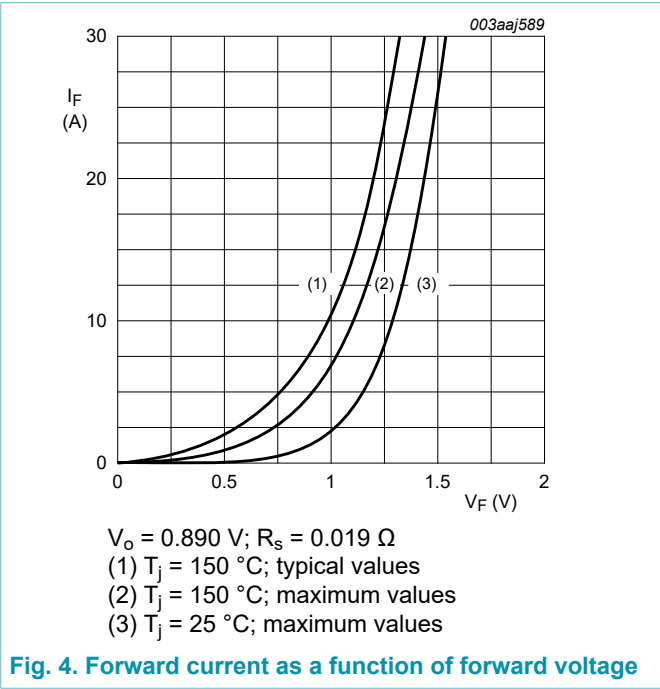


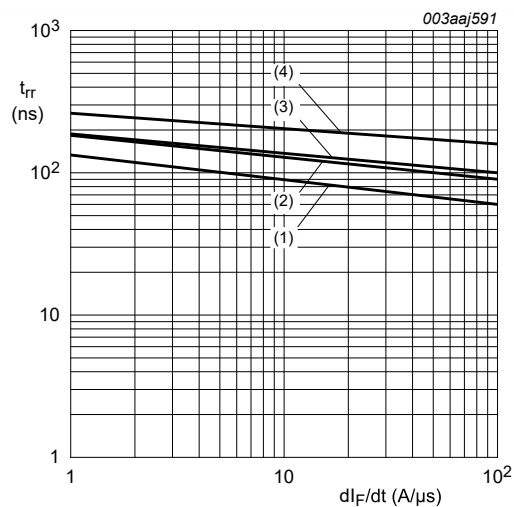
Fig. 3. Transient thermal impedance from junction to mounting base as a function of pulse width

9. Characteristics

Table 6. Characteristics

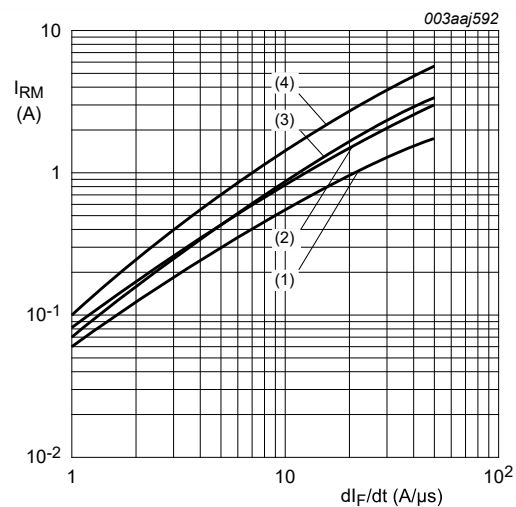
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 8 A; T _J = 150 °C; Fig. 4		-	0.9	1.03	V
		I _F = 8 A; T _J = 25 °C; Fig. 4		-	1.05	1.25	V
		I _F = 20 A; T _J = 25 °C; Fig. 4		-	1.2	1.4	V
I _R	reverse current	V _R = 500 V; T _J = 25 °C		-	2	50	μA
		V _R = 500 V; T _J = 100 °C		-	0.1	0.35	mA
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/s; T _J = 25 °C; Fig. 5 ; Fig. 6		-	50	60	ns
I _{RM}	peak reverse recovery current	I _F = 10 A; V _R = 30 V; dI _F /dt = 50 A/s; T _J = 100 °C; Fig. 5 ; Fig. 7		-	4	5.5	A
Q _r	recovered charge	I _F = 2 A; V _R = 30 V; dI _F /dt = 20 A/s; T _J = 25 °C; Fig. 8 ; Fig. 5		-	40	60	nC
V _{FR}	forward recovery voltage	I _F = 10 A; dI _F /dt = 10 A/s; T _J = 25 °C; Fig. 9		-	2.5	-	V





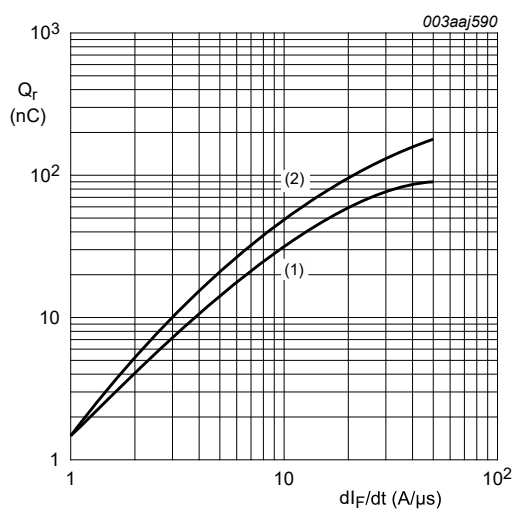
- (1) $I_F = 1 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$
 (2) $I_F = 1 \text{ A}; T_j = 100 \text{ }^\circ\text{C};$
 (3) $I_F = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$
 (4) $I_F = 10 \text{ A}; T_j = 100 \text{ }^\circ\text{C}$

Fig. 6. Reverse recovery time as a function of rate of change of forward current; maximum values



- (1) $I_F = 1 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$
 (2) $I_F = 1 \text{ A}; T_j = 100 \text{ }^\circ\text{C};$
 (3) $I_F = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$
 (4) $I_F = 10 \text{ A}; T_j = 100 \text{ }^\circ\text{C}$

Fig. 7. Peak reverse recovery current as a function of rate of change of forward current; maximum values



- (1) $I_F = 2 \text{ A}; T_j = 25 \text{ }^\circ\text{C};$
 (2) $I_F = 10 \text{ A}; T_j = 25 \text{ }^\circ\text{C}$

Fig. 8. Recovered charge as a function of rate of change of forward current; maximum values

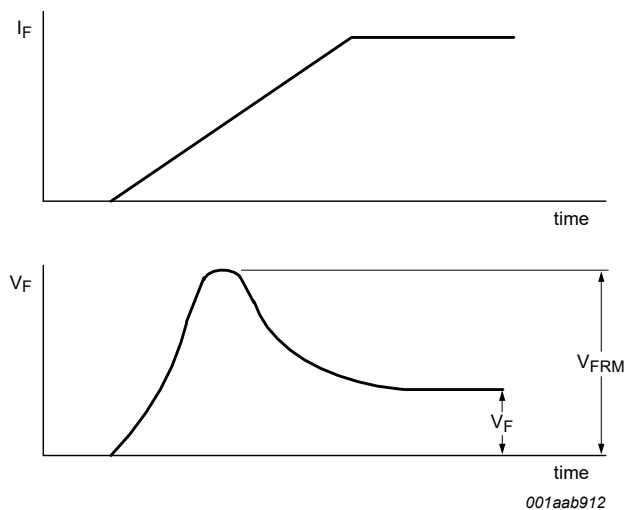


Fig. 9. Forward recovery definitions

10. Package outline

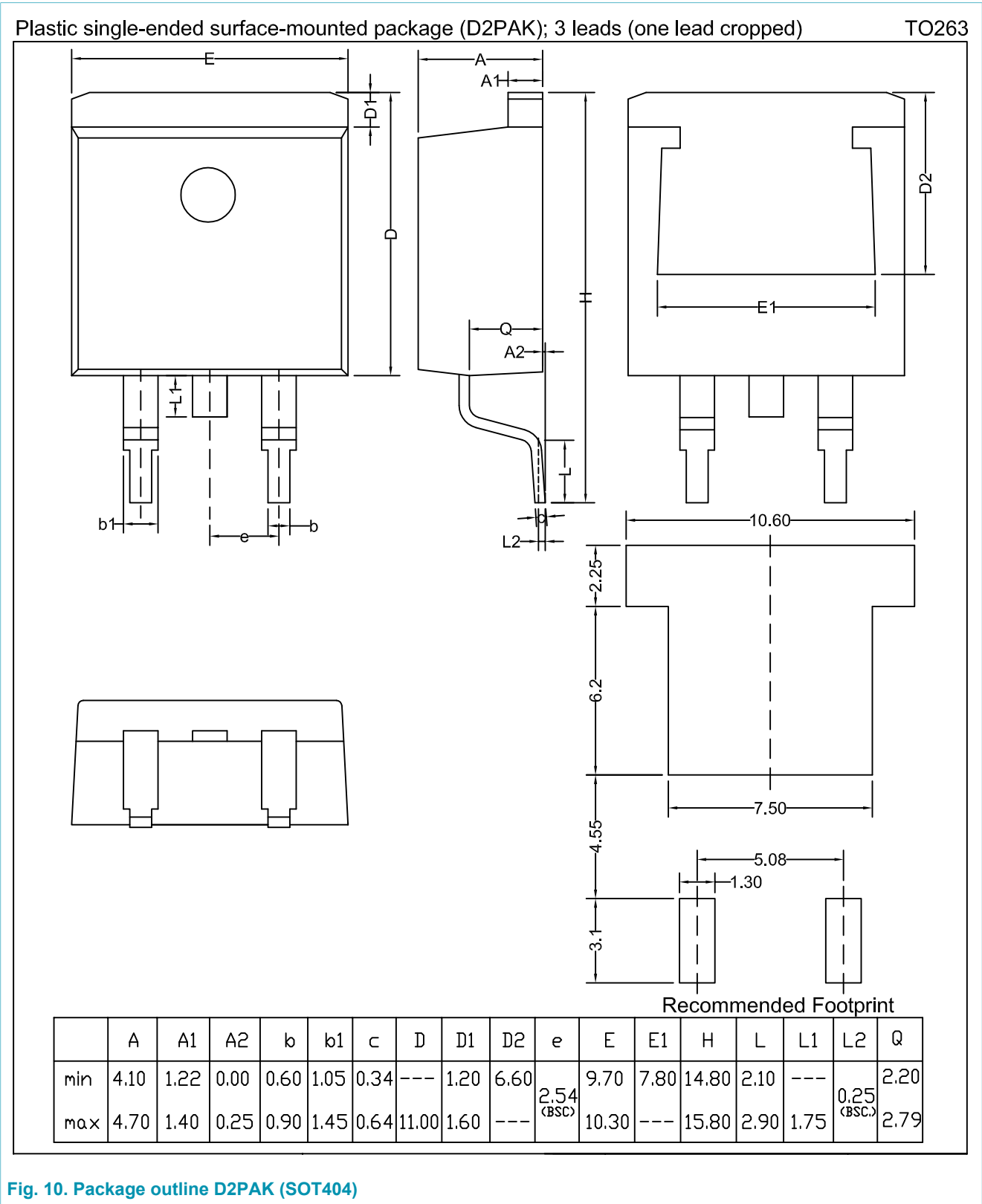


Fig. 10. Package outline D2PAK (SOT404)

11. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

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- [2] The term 'short data sheet' is explained in section "Definitions".
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